

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM365327

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	Security Agreement		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
VISHAY DALE ELECTRONICS, LLC		12/10/2015	LIMITED LIABILITY COMPANY: DELAWARE
RECEIVING PARTY DATA			
Name:	JPMorgan Chase Bank, N.A., as Administrative Agent		
Street Address:	270 PARK AVENUE		
City:	NEW YORK		
State/Country:	NEW YORK		
Postal Code:	10017		
Entity Type:	ASSOCIATION: UNITED STATES		
PROPERTY NUMBERS Total: 5			
Property Type	Number	Word Mark	
Registration Number:	1383220	DALE	
Registration Number:	3394307	IHLP	
Registration Number:	2074628	POWER METAL STRIP	
Registration Number:	3431324	WSL	
Registration Number:	3264991	WSR	
CORRESPONDENCE DATA			
Fax Number:	8668265420		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>			
Phone:	301-638-0511		
Email:	ipresearchplus@comcast.net		
Correspondent Name:	IP Research Plus, Inc.		
Address Line 1:	21 Tadcaster Circle		
Address Line 2:	attn: Penelope J.A. Agodoa		
Address Line 4:	Waldorf, MARYLAND 20602		
ATTORNEY DOCKET NUMBER:	CRS1-40693		
NAME OF SUBMITTER:	Penelope J.A. Agodoa		
SIGNATURE:	/pja/		
DATE SIGNED:	12/10/2015		

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Total Attachments: 15

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PATENT AND TRADEMARK SECURITY AGREEMENT dated as of December 10, 2015 (this "Agreement"), among Vishay Intertechnology, Inc. (the "Company"), the Domestic Subsidiaries of the Company listed on the signature pages hereto (collectively, together with the Company, the "Grantors") and JPMORGAN CHASE BANK, N.A. ("JPMCB"), as Administrative Agent.

Reference is made to (a) the Credit Agreement dated as of December 1, 2010, as amended and restated as of August 8, 2013, and as further amended and restated as of the date hereof (as further amended, restated, amended and restated, supplemented or otherwise modified from time to time, the "Credit Agreement"), among the Company, the Subsidiary Borrowers from time to time party thereto, the Lenders from time to time party thereto and JPMCB, as Administrative Agent, and (b) Guarantee and Collateral Agreement dated as of December 1, 2010, as amended by that certain Reaffirmation Agreement dated as of August 8, 2013 among the Company, the subsidiaries of the Company party thereto and JPMCB, as Administrative Agent (as further amended, restated, supplemented or otherwise modified from time to time, the "Collateral Agreement"), among the Company, the Domestic Subsidiary Loan Parties from time to time party thereto and JPMCB, as Administrative Agent. The Lenders and Issuing Banks have extended, and have agreed to extend, credit to the Borrowers on the terms and subject to the conditions set forth in the Credit Agreement. The obligations of the Lenders and the Issuing Banks to extend such credit are conditioned upon, among other things, the execution and delivery of this Agreement. The Grantors are Affiliates of the Borrowers, will derive substantial benefits from the extension of credit to the Borrowers under the Credit Agreement and are willing to execute and deliver this Agreement in order to induce the Lenders and Issuing Banks to extend such credit. Accordingly, the parties hereto agree as follows:

SECTION 1. Terms. Each capitalized term used but not otherwise defined herein shall have the meaning specified in the Credit Agreement or the Collateral Agreement, as applicable. The rules of construction specified in Section 1.03 of the Credit Agreement also apply to this Agreement, mutatis mutandis.

SECTION 2. Grant of Security Interest. As security for the payment or performance, as the case may be, in full of the Secured Obligations, each Grantor, pursuant to the Collateral Agreement, did and hereby does grant to the Administrative Agent, its successors and assigns, for the benefit of the Secured Parties, a security interest in all right, title and interest in, to and under any and all of the following assets and properties now owned or at any time hereafter acquired by such Grantor or in which such Grantor now has or at any time hereafter may acquire any right, title or interest (collectively, the "Patent and Trademark Collateral"):

(a) all letters patent of the United States, all registrations and recordings thereof, and all applications for letters patent of the United States, including registrations,

recordings and pending applications in the United States Patent and Trademark Office, including those listed on Schedule I;

(b) all reissues, continuations, divisions, continuations-in-part, renewals or extensions thereof, and the inventions disclosed or claimed therein, including the right to make, use and/or sell the inventions disclosed or claimed therein;

(c) all trademarks, service marks, trade names, corporate names, company names, business names, fictitious business names, trade styles, trade dress, logos, other source or business identifiers, designs and general intangibles of like nature, now existing or hereafter adopted or acquired, all registrations and recordings thereof, and all registration and recording applications filed in connection therewith, including registrations and registration applications in the United States Patent and Trademark Office or any similar offices in any State of the United States, and all extensions or renewals thereof, including those listed on Schedule II;

(d) all goodwill associated therewith or symbolized thereby; and

(e) all other assets, rights and interests that uniquely reflect or embody such goodwill;

provided, however, that notwithstanding the foregoing, in no event shall the Patent and Trademark Collateral include any Excluded IP Collateral.

SECTION 3. Collateral Agreement. The security interests granted to the Administrative Agent herein are granted in furtherance, and not in limitation of, the security interests granted to the Administrative Agent pursuant to the Collateral Agreement. Each Grantor hereby acknowledges and affirms that the rights and remedies of the Administrative Agent with respect to the Patent and Trademark Collateral are more fully set forth in the Collateral Agreement, the terms and provisions of which are hereby incorporated herein by reference as if fully set forth herein. In the event of any conflict between the terms of this Agreement and the Collateral Agreement, the terms of the Collateral Agreement shall govern.

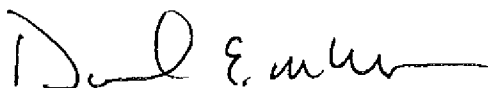
SECTION 4. Counterparts. This Agreement may be executed in counterparts (and by different parties hereto on different counterparts), each of which shall constitute an original, but all of which when taken together shall constitute a single contract. Delivery of an executed counterpart to a signature page of this Agreement by facsimile or other electronic imaging shall be effective as delivery of a manually executed counterpart of this Agreement.

SECTION 5. Governing Law. This Agreement shall be construed in accordance with and governed by the law of the State of New York.

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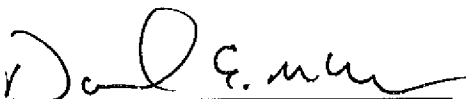
IN WITNESS WHEREOF, the parties hereto have duly executed this Agreement as of the day and year first above written.

VISHAY INTERTECHNOLOGY, INC.,

by 

Name: David E. McConnell
Title: Vice President and Corporate
Treasurer

VISHAY DALE ELECTRONICS, LLC,

by 

Name: David E. McConnell
Title: Authorized Signatory

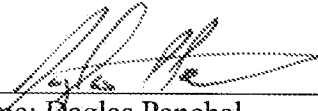
[Signature Page to Patent and Trademark Security Agreement]

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TRADEMARK
REEL: 005686 FRAME: 0281

JPMORGAN CHASE BANK, N.A., as
Administrative Agent,

by



Name: Douglas Panchal
Title: Vice President

[Signature Page to Patent and Trademark Security Agreement]

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TRADEMARK
REEL: 005686 FRAME: 0282

SCHEDULE I
PATENTS

(a) U.S. Patent Registrations and Patent Applications

* Some of the patents listed below have been filed with the USPTO under Dale Electronics, Inc. or Vishay Dale Electronics, Inc. or Vishay Dale Electronics, Inc. on June 4, 1997 and to Vishay Dale Electronics, LLC on March 26, 2015.

	Type	Serial No.	Patent No.	Title: (Patent Description)	Status	File Date	Issue Date	Domestic Loan Party
1.	UTL	09/448,676	6,201,215	THE METHOD OF MAKING A THICK FILM LOW VALUE HIGH FREQUENCY INDUCTOR	ISSUED	11/24/1999	3/13/2001	Vishay Dale Electronics, Inc.
2.	UTL	09/247,490	5,999,085	SURFACE MOUNTED FOUR TERMINAL RESISTOR	ISSUED	2/10/1999	12/7 /1999	Vishay Dale Electronics, Inc.
3.	UTL	09/271,748	6,198,375	INDUCTOR COIL STRUCTURE	ISSUED	3/18/1999	3/6 /2001	Vishay Dale Electronics, Inc.
4.	UTL	09/546,859	6,449,829	METHOD FOR MAKING INDUCTOR COIL STRUCTURE	ISSUED	4/10/2000	9/17/2002	Vishay Dale Electronics, Inc.
5.	UTL	10/244,777	6,946,944	INDUCTOR COIL AND METHOD FOR MAKING SAME	ISSUED	9/16/2002	9/20/2005	Vishay Dale Electronics, Inc.
6.	UTL	11/038,880	7,034,645	INDUCTOR COIL AND METHOD FOR MAKING SAME	ISSUED	1/20/2005	4/25/2006	Vishay Dale Electronics, Inc.
7.	UTL	11/409,651	7,221,249	INDUCTOR COIL	ISSUED	4/24/2006	5/22/2007	Vishay Dale Electronics, Inc.

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title: (Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
8.	UTL	11/609,165	7,263,761	METHOD FOR MAKING A HIGH CURRENT LOW PROFILE INDUCTOR	ISSUED	12/11/2006	9/4 /2007	Vishay Dale Electronics, Inc.
9.	UTL	11/782,020	7,345,562	METHOD FOR MAKING A HIGH CURRENT LOW PROFILE INDUCTOR	ISSUED	7/24/2007	3/18/2008	Vishay Dale Electronics, Inc.
10.	UTL	12/013,725	7,921,546	METHOD FOR MAKING A HIGH CURRENT LOW PROFILE INDUCTOR	ISSUED	1/11/4/2008	4/12/2011	Vishay Dale Electronics, Inc.
11.	UTL	12/535,757	7,986,207	METHOD FOR MAKING A HIGH CURRENT LOW PROFILE INDUCTOR	ISSUED	8/5/2009	7/26/2011	Vishay Dale Electronics, Inc.
12.	UTL	09/471,622	6,401,329	METHOD FOR MAKING OVERLAY SURFACE MOUNT RESISTOR	ISSUED	12/21/1999	6/11/2002	Vishay Dale Electronics, Inc.
13.	UTL	09/715,252	6,441,718	OVERLAY SURFACE MOUNT RESISTOR	ISSUED	11/17/2000	8/27/2002	Vishay Dale Electronics, Inc.
14.	UTL	10/078,311	6,725,529	METHOD FOR MAKING OVERLAY SURFACE MOUNT RESISTOR	ISSUED	2/18/2002	4/27/2004	Vishay Dale Electronics, Inc.
15.	UTL	10/797,866	6,901,655	METHOD FOR MAKING OVERLAY SURFACE MOUNT RESISTOR	ISSUED	3/10/2004	6/7 /2005	Vishay Dale Electronics, Inc.
16.	UTL	09/471,617	6,510,605	METHOD FOR MAKING FORMED SURFACE MOUNT RESISTOR	ISSUED	12/21/1999	1/28/2003	Vishay Dale Electronics, Inc.
17.	UTL	10/079,010	7,170,389	APPARATUS FOR TANTALUM PENTOXIDE MOISTURE BARRIER IN FILM RESISTORS	ISSUED	2/19/2002	1/30/2007	Vishay Dale Electronics, Inc.

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title: (Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
18.	UTL	09/811,844	7,038,572	POWER CHIP RESISTOR	ISSUED	3/19/2001	5/2/2006	Vishay Dale Electronics, Inc.
19.	UTL	10/441,649	7,102,484	HIGH POWER RESISTOR HAVING AN IMPROVED OPERATING TEMPERATURE RANGE AND METHOD OF MAKING SAME	ISSUED	5/20/2003	9/5/2006	Vishay Dale Electronics, Inc.
20.	UTL	10/744,846	6,925,704	METHOD FOR MAKING HIGH POWER RESISTOR HAVING IMPROVED OPERATING TEMPERATURE RANGE	ISSUED	12/23/2003	8/9/2005	Vishay Dale Electronics, Inc.
21.	UTL	11/123,508	7,042,328	HIGH POWER RESISTOR HAVING AN IMPROVED OPERATING TEMPERATURE RANGE	ISSUED	5/5/2005	5/9/2006	Vishay Dale Electronics, Inc.
22.	UTL	11/066,865	7,190,252	SURFACE MOUNT ELECTRICAL RESISTOR WITH THERMALLY CONDUCTIVE, ELECTRICALLY INSULATIVE FILLER AND METHOD FOR USING SAME	ISSUED	2/25/2005	3/13/2007	Vishay Dale Electronics, Inc.
23.	UTL	11/535,758	8,018,310	INDUCTOR WITH THERMALLY STABLE RESISTANCE	ISSUED	9/27/2006	9/13/2011	Vishay Dale Electronics, Inc.
24.	UTL	11/862,572		POWER RESISTOR	PUBLISHED	9/27/2007		Vishay Dale Electronics, Inc.
25.	UTL	12/026,939		RESISTOR AND METHOD FOR MAKING SAME	ISSUED	2/6/2008	3/22/2011	Vishay Dale Electronics, Inc.

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title: (Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
26.	UTL	12/205,197	8,242,878	RESISTOR AND METHOD FOR MAKING SAME	ISSUED	9/5/2008	8/14/2012	Vishay Dale Electronics, Inc.
27.	UTL	12/536,792	8,248,202	METAL STRIP RESISTOR FOR MITIGATING EFFECTS OF THERMAL EMF	ISSUED	8/6/2009	8/21/2012	Vishay Dale Electronics, Inc.
28.	UTL	12/874,514	8,198,977	RESISTOR WITH TEMPERATURE COEFFICIENT OF RESISTANCE (TCR) COMPENSATION	ISSUED	9/2/2010	6/12/2012	Vishay Dale Electronics, Inc.
29.	UTL	12/650,079	8,325,007	SURFACE MOUNT RESISTOR WITH TERMINALS FOR HIGH POWER DISSIPATION AND METHOD FOR MAKING SAME	ISSUED	12/30/2009	12/4/2012	Vishay Dale Electronics, Inc.
30.	UTL	13/051,585	8,344,843	RESISTOR AND METHOD FOR MAKING SAME	ISSUED	3/18/2011	1/1/2013	Vishay Dale Electronics, Inc.
31.	UTL	13/127,838	8,581,687	FOUR-TERMINAL RESISTOR WITH FOUR RESISTORS AND ADJUSTABLE TEMPERATURE COEFFICIENT OF RESISTANCE	ISSUED	5/5/2011	11/12/2013	Dale Electronics, Inc.
32.	UTL	13/109,576		METHOD FOR MAKING A HIGH CURRENT LOW PROFILE INDUCTOR	PENDING	5/17/2011		Vishay Dale Electronics, Inc.

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title: (Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
33.	UTL	13/198,274	8,378,772	INDUCTOR WITH THERMALLY STABLE RESISTANCE	ISSUED	8/4/2011	2/19/2013	Vishay Dale Electronics, Inc.
34.	UTL	13/213,877		HIGH POWERED INDUCTORS USING A MAGNETIC BIAS	PENDING	8/19/2011		Vishay Dale Electronics, Inc.
35.	PRV	61/591,018		INTEGRATED CIRCUIT ELEMENT AND ELECTRONIC CIRCUIT FOR LIGHT EMITTING DIODE APPLICATIONS	PENDING	1/26/2012		Vishay Dale Electronics, Inc.
36.	UTL	13/493,402	8,525,637	RESISTOR WITH TEMPERATURE COEFFICIENT OF RESISTANCE (TCR) COMPENSATION	ISSUED	6/11/2012	9/3/2013	Vishay Dale Electronics, Inc.
37.	UTL	13/462,958	9,001,512	HEAT SPREADER FOR ELECTRICAL COMPONENTS	ISSUED	5/3/2012	4/7/2015	Vishay Dale Electronics, LLC
38.	UTL	13/600,770		HIGHLY COUPLED INDUCTOR	PENDING	8/31/2012		Vishay Dale Electronics, Inc.
39.	UTL	13/569,721	8,686,828	RESISTOR AND METHOD FOR MAKING SAME	ISSUED	8/8/2012	4/1/2014	Dale Electronics, Inc.
40.	UTL	12,950,177	8,319,598	POWER RESISTOR	ISSUED	11/19/2010	11/27/2012	Vishay Dale Electronics, Inc.
41.	UTL	13/720,618		METHOD FOR MAKING INDUCTOR COIL STRUCTURE	PENDING	12/19/2012		Vishay Dale Electronics, Inc.

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title: (Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
42.	UTL	13,689,928		SURFACE MOUNT RESISTOR WITH TERMINALS FOR HIGH POWER DISSIPATION AND METHOD FOR MAKING SAME	PENDING	11/30/2012		Vishay Dale Electronics, Inc.
43.	UTL	13/768,039	8,975,994	INDUCTOR WITH THERMALLY STABLE RESISTANCE	ISSUED	2/15/2013	3/10/2015	Dale Electronics, Inc.
44.	UTL	13/750,404		INTEGRATED CIRCUIT ELEMENT AND ELECTRONIC CIRCUIT FOR LIGHT EMITTING DIODE APPLICATIONS	PENDING	1/25/2013		Vishay Dale Electronics, Inc.
45.	UTL	13/750,762		LOW PROFILE HIGH CURRENT COMPOSITE TRANSFORMER	PENDING	1/25/2013		Vishay Dale Electronics, Inc.
46.	PRV	61/752,278		ELECTRONIC MODULE AND METHOD FOR MAKING SAME	PENDING	1/14/2013		Vishay Dale Electronics, Inc.
47.	UTL	14/015,488	8,878,643	RESISTOR WITH TEMPERATURE COEFFICIENT OF RESISTANCE (TCR) COMPENSATION	ISSUED	8/30/2013	11/4/2014	Vishay Dale Electronics, Inc.
48.	UTL	14/228,780		RESISTOR AND METHOD FOR MAKING SAME	PENDING	3/28/2014		Dale Electronics, Inc.
49.	UTL	14/203,234		RESISTOR AND METHOD OF MANUFACTURE	PENDING	3/10/2014		Vishay-Dale
50.	UTL	13/730,155	8,730,003	RESISTOR AND METHOD FOR MAKING SAME	ISSUED	12/28/2012	5/20/2014	Dale Electronics, Inc.

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title: (Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
51.	UTL	14/242,982		MAGNETIC COMPONENTS AND METHODS FOR MAKING SAME	PENDING	4/2/2014		Dale Electronics, Inc.
52.	UTL	14/280,230		RESISTOR AND METHOD FOR MAKING SAME	PENDING	5/16/2014		Dale Electronics, Inc.
53.	UTL	14/287,883		EDGE-WOUND RESISTOR, RESISTOR ASSEMBLY, AND METHOD OF MAKING SAME	PENDING	5/27/2014		Dale Electronics, Inc.
54.	Design	29/491,946		EDGE-WOUND RESISTOR	PENDING	5/27/2014		Dale Electronics, Inc.
55.	UTL	13/725,018	8,823,483	POWER RESISTOR WITH INTEGRATED HEAT SPREADER	ISSUED	12/21/2012	9/2/2014	Dale Electronics, Inc.
56.	UTL	14/473,118		POWER RESISTOR WITH INTEGRATED HEAT SPREADER	PENDING	8/29/2014		Dale Electronics, Inc.
57.	UTL	14/531,505		RESISTOR WITH TEMPERATURE COEFFICIENT OF RESISTANCE (TCR) COMPENSATION	PENDING	11/3/2014		Vishay Dale Electronics, Inc.
58.	UTL	14/563,560		THERMALLY SPRAYED THIN FILM RESISTOR AND METHOD OF MAKING	PENDING	12/8/2014		Vishay Dale Electronics, Inc.

	<u>Type</u>	<u>Serial No.</u>	<u>Patent No.</u>	<u>Title: (Patent Description)</u>	<u>Status</u>	<u>File Date</u>	<u>Issue Date</u>	<u>Domestic Loan Party</u>
59.	Prov	62/202,580		MOLDED PASSIVE COMPONENT FOR HIGH VOLTAGE APPLICATIONS	PENDING	8/7/2015		Dale Electronics, Inc.

License Agreements (Patents)

	<u>Name of Licensor</u>	<u>Name of Agreement</u>	<u>Date of Agreement</u>	<u>Parties to Agreement:</u>
1.	Vishay Dale Electronics, Inc.	Non-Exclusive Patent License Agreement	October 1, 2004	Vishay Dale Electronics, Inc. (as licensor) and KOA Corporation and KOA Speer Electronics, Inc. (each as a licensee)
2.	Vishay Dale Electronics, Inc.	Non-Exclusive License (of certain Patents and Patent Applications as listed in the agreement)	Effective date of January 22, 2007	Vishay Dale Electronics, Inc. (as Licensor) and Toko, Inc. and Toko America, Inc. (each as a licensee)
3.	Vishay Dale Electronics, Inc.	Non-Exclusive License Agreement and side letter (of certain Patent Rights as defined in the agreement and listed in Schedule A thereto)	Effective date of January 1, 2009	Vishay Dale Electronics, Inc. (as licensor) and Cyntec Co. Ltd. (as licensee)
4.	Vishay Dale Electronics, Inc.	Settlement, Mutual Release and License Agreement (of certain patents and patent applications listed in Schedule A of the agreement) as modified by letter agreement dated as of October 8, 2009 between the parties (with Mag Layer)	Effective date of October 8, 2009	Vishay Dale Electronics, Inc. (as licensor) and Mag Layers Scientific-Technics Co., Ltd. (as licensee)

	<u>Name of Licensor</u>	<u>Name of Agreement</u>	<u>Date of Agreement</u>	<u>Parties to Agreement:</u>
5.	Vishay Dale Electronics, Inc.	Settlement, Mutual Release and License Agreement (Superworld)	October 1, 2010	Vishay Dale Electronics, Inc. (as licensor) and Taipag Electronics Co. Ltd. (as licensee)
6.	Vishay Dale Electronics, Inc.	Patent License Agreement	July 6, 2010	Vishay Dale Electronics, Inc. (as licensor) and Vishay Precision Group, Inc. (as licensee)
7.	Vishay Dale Electronics, Inc.	Non-Exclusive License Agreement	October 1, 2009	Vishay Dale Electronics, Inc. (as licensor) and Prejection Industrial Corp. (as licensee)
8.	Vishay Dale Electronics, Inc.	Non-Exclusive License Agreement	March 12, 2010	Vishay Dale Electronics, Inc. (as licensor) and BI Technologies Corporation (as licensee)
9.	Vishay Dale Electronics, Inc.	Settlement, Mutual Release and License Agreement	July 1, 2010	Vishay Dale Electronics, Inc. (as licensor) and Magic Tech Co., Ltd. (as licensee)
10.	Vishay Dale Electronics, Inc.	Non-Exclusive Patent Agreement	June 24, 2004	Vishay Dale Electronics, Inc. (as licensor) and Electronica Dale de Mexico S.A. De C.V. (as licensee)
11.	Vishay Dale Electronics, Inc.	Non-Exclusive License Agreement	Effective date of December 31, 2012	Vishay Dale Electronics, Inc. (as licensor) and TRIO Technology Co., Ltd. (as licensee)
12.	Vishay Dale Electronics, Inc.	Amended and Restated Non-Exclusive License Agreement	January 10, 2013	Vishay Dale Electronics, Inc. (as licensor) and AOA Technology (M) Sdn. Bhd. (as licensee) and ABC Taiwan Electronics Corp. (as co-licensee)
13.	Vishay Dale Electronics, Inc.	Vishay Non-Exclusive License Agreement	Effective date of January 14, 2013	Vishay Dale Electronics, Inc. (as licensor) and Chilisim Electronics Corporation (as licensee)
14.	Vishay Dale Electronics, Inc.	Non-Exclusive License Agreement	Effective date as of February 28, 2013	Vishay Dale Electronics, Inc. (as licensor) and Hotline (Shenzhen)

<u>Name of Licensor</u>	<u>Name of Agreement</u>	<u>Date of Agreement</u>	<u>Parties to Agreement:</u>
15 Vishay Dale Electronics, Inc.	Amended and Restated Non-Exclusive License Agreement	October 12, 2011	Electronic Co., LTD (as licensee) Vishay Dale Electronics, Inc. (as licensor) and 3L Electronic (USA), Inc. (as licensee)

SCHEDULE II
TRADEMARKS

Trademarks and Trademark Applications

* Some of the trademarks listed below have been filed with the USPTO under Dale Electronics, Inc. or Vishay Dale Electronics, Inc. Dale Electronics, Inc. changed its name to Vishay Dale Electronics, Inc. on June 4, 1997 and to Vishay Dale Electronics, LLC on March 26, 2015.

No.	Trademark	Legal Owner	Country	Reg.#	Reg. Date
1.	DALE	Vishay Dale Electronics, Inc.	United States	1383220	2/18/1986
2.	IHLP	Vishay Dale Electronics, Inc.	United States	3394307	3/11/2008
3.	POWER METAL STRIP	Vishay Dale Electronics, Inc.	United States	2074628	6/24/1997
4.	WSL	Vishay Dale Electronics, Inc.	United States	3431324	5/20/2008
5.	WSR	Vishay Dale Electronics, Inc.	United States	3264991	7/17/2007

License Agreements (Trademarks)

None.